

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	507	(multidie or multi-die or stacked near die) near2 package	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 08:46
L2	235	(interposer or substrate or package) near2 (recess or opening or indent or aperture or recessed or depression or depressed or receptacle) near2 (die or ic) and (multidie or (plural or plurality or multiple or multi or second or secondary) near (die or ic))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 09:12
L3	199	(interposer or substrate or package) near2 (cavity) near2 (die or ic) and (multidie or (plural or plurality or multiple or multi or second or secondary) near (die or ic))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 09:24
L4	498	(interposer) and (opening or aperture or hole or thruhole or cavity) near3 (wirebond or wire or wiring or bond) and (multichip or (stacked or plural or multi or multiple or plurality or second or two or third or three) near (chip or die or ic))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 09:43
L5	36	(US-20020079568-\$ or US-20040009631-\$ or US-20010004128-\$ or US-20030025199-\$ or US-20030085463-\$ or US-20030207516-\$ or US-20020047196-\$ or US-20040159955-\$ or US-20020109237-\$ or US-20020127770-\$ or US-20040084771-\$ or US-20020074630-\$ or US-20010036711-\$).did. or (US-6731015-\$ or US-6291267-\$ or US-6448506-\$ or US-5963794-\$ or US-5869894-\$ or US-6365963-\$ or US-6506633-\$ or US-6452278-\$ or US-5949135-\$ or US-6678167-\$ or US-6343019-\$ or US-5886412-\$ or US-5477082-\$ or US-6104089-\$ or US-5608262-\$ or US-6693362-\$ or US-6659512-\$ or US-6388333-\$ or US-6294406-\$ or US-6791195-\$ or US-6057594-\$ or US-5869889-\$).did. or (EP-1122786-\$).did.	US-PGPUB; USPAT; EPO	OR	ON	2006/09/22 09:48

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L6	333	(interposer or substrate) near10 (aperture or opening or hole or window) near3 ((wire or wiring) near (bond or bonding) or wirebonds) near5 (chip or die or ic)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 10:09
L7	202	(interposer or carrier near substrate) and (mcm or multichip or multдие or (plural or multiple or stacked or plurality or multi or bottom or back) near2 (chip or die or ic or module)) and (interposer or carrier or substrate) near2 (aperture or opening or recess or receptacle or window) near2 (chip or die or ic or wirebond or bonding near wire or wire near bond or pillar or interconnect)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 10:28
L8	49	(dual or double or two) near (side or sided) near2 interposer	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 10:38
L9	34	(front or top or upper or first or parent or higher) near (chip or die or ic) near3 (bottom or back or lower or second or child or daughter) near (chip or die or ic) near3 (bonded or joined or connection or connected or connecting or wirebond or wirebonded or interconnect\$3 or wired) near5 (through or thru) near4 (substrate or interposer or carrier or pcb or pwb or wiring adj board or circuit adj board)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 10:43
L10	474	(carrier near substrate or interposer or wiring near board or wiring near substrate) near5 (cavity or aperture or opening or depression or recess or hole or receptacle) near (die or chip or ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 10:46
L15	120	(film or tape or resin or polyimide) near3 (substrate or carrier) near15 (tab or tape near automated near bonding) same (rigid\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 11:12

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L16	403	257/723.ccls. and (die or ic or chip) near2 (recess or recessed or cavity or hole or aperture or opening or receptacle or socket or depression or depressed or indent or indentation or trench)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 11:37
L17	216	257/724.ccls. and (die or ic or chip) near2 (recess or recessed or cavity or hole or aperture or opening or receptacle or socket or depression or depressed or indent or indentation or trench)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 12:37
L18	845	257/782.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 12:03
L19	374	257/777.ccls. and (die or ic or chip) near2 (recess or recessed or cavity or hole or aperture or opening or receptacle or socket or depression or depressed or indent or indentation or trench)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 12:57
L20	213	257/786.ccls. and (die or ic or chip) near2 (recess or recessed or cavity or hole or aperture or opening or receptacle or socket or depression or depressed or indent or indentation or trench)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 13:08
L21	5	"5977640".pn. "6441495".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 13:08
L22	1322	438/107.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 13:21
L23	247	438/107.ccls. and (die or ic or chip) near2 (recess or recessed or cavity or hole or aperture or opening or receptacle or socket or depression or depressed or indent or indentation or trench)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 13:21
L24	1656	438/108.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 13:42

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L25	319	438/108.ccls. and (die or ic or chip) near2 (recess or recessed or cavity or hole or aperture or opening or receptacle or socket or depression or depressed or indent or indentation or trench)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 13:42
L26	966	438/109.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 13:42
L27	184	438/109.ccls. and (die or ic or chip) near2 (recess or recessed or cavity or hole or aperture or opening or receptacle or socket or depression or depressed or indent or indentation or trench)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 13:52
L28	2277	438/107,108,109.ccls. and ((die or ic or chip) near2 (plural or plurality or multi or multiple or dual or two or second or stacked) or mcm or multдие)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 13:55
L29	279	438/107,108,109.ccls. and ((die or ic or chip) near2 (plural or plurality or multi or multiple or dual or two or second or stacked) or mcm or multдие) near5 (interposer or carrier)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 14:11
L31	311	257/E23.169.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 14:27
L32	325	257/E23.175.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 14:27

Interference Search

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L33	198	((interposer or carrier) near5 (opening or aperture or receptacle or indent or depression or cavity or recess or recessed or socket) near4 (chip or die or ic)).clm.	US-PGPUB	OR	ON	2006/09/22 14:31
L35	103	((interposer or carrier) and ((multiple or plural or multi or plurality or stacked) near2 (chip or die or ic) or multidi or mcm) and (chip or die or ic) near2 (receptacle or opening or recess or recessed or indent or indentation or aperture or depression or socket or cavity)).clm.	US-PGPUB	OR	ON	2006/09/22 14:34
L38	65	((interposer or carrier) and (die or chip or ic) near2 (bottom or lower or below) and (die or chip or ic) near2 (top or upper or above) and (chip or die or ic) near2 (plural or plurality or multi or multiple or second or secondary or dual or stack or stacked)).clm.	US-PGPUB	OR	ON	2006/09/22 14:36
L39	6	((interposer or carrier) and (die or chip or ic) near2 (inside or within or embedded or embedding or contained or enclosed or engulfed or enclosing) near3 (cavity or receptacle or opening or aperture or recess or recessed or depression or socket) and (die or chip or ic) near2 (top or upper or above) and (chip or die or ic) near2 (plural or plurality or multi or multiple or second or secondary or dual or stack or stacked)).clm.	US-PGPUB	OR	ON	2006/09/22 14:37